



**DOCUMENT TITLE:  
DS2502X1 CHIP SCALE PACKAGE, PACKAGE CODE: BF211-2**

**DOC ID # 21-0379                      NEW REV:    A**

**ECN#: HQ-08-5741                      EFFECTIVE DATE: 07/15/08**

**ORIGINATOR: JEFF WALKER**

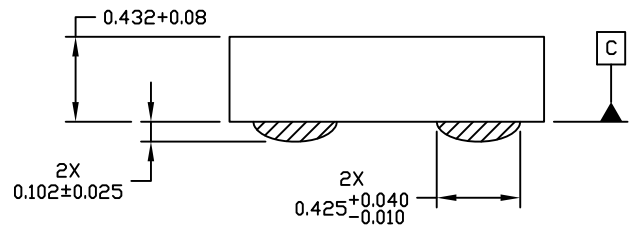
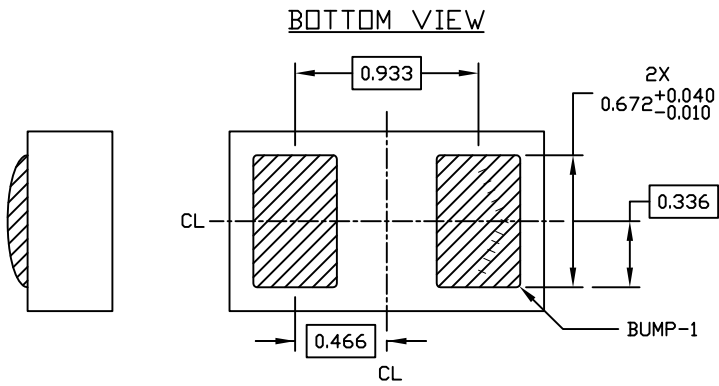
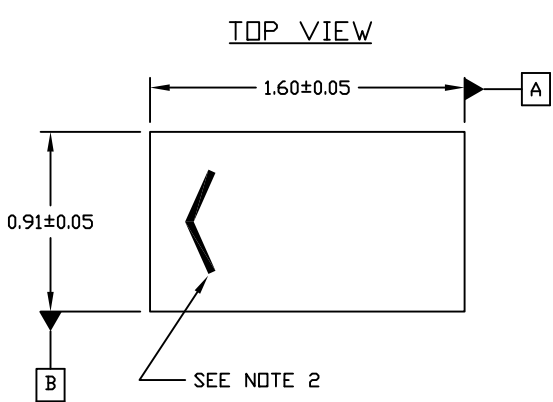
**MOST RECENT CHANGES**

<b>FROM</b>	<b>TO</b>
DALLAS DOCUMENT CONTROL SYSTEM DOC ID# 56-G7010-001 LOGO-DALLAS/MAXIM	INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL LOGO-MAXIM

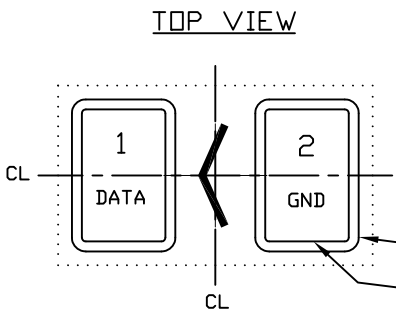
REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED

NOTES:

1. DIMENSIONS: MM [INCH]
2. LASER MARK
3. LANDING PAD NOT DEFINED BY SOLDER MASK



0.075	Ⓜ	C	A	Ⓢ	B	Ⓢ
0.010	Ⓜ	C				



RECOMMENDED SUBSTRATE LAND PATTERN

PAD SIZE 0.53X0.78 [0.021X0.031]  
SEE NOTE 3  
SOLDER PASTE APERTURE 0.43X0.68 [0.017X0.027]

SIGNATURE	DATE
QA APVD:	
ENGR MGR:	
ENGR BY:	B. MCCARTY 04/99
CHECK BY:	S CHINNUSAMY 10/06
DRAWN BY:	B. MCCARTY 04/99



DS2502X1 CHIP SCALE PACKAGE  
PACKAGE CODE: BF211-2

SIZE A	FSCM NO.	DWG NO. 21-0379	REV A
SCALE NONE	SHEET 1 / 1		

### REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	ECN# HQ-08-5741. INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL. LOGO-MAXIM	07/15/08	JW



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**DOCUMENT I.D.**  
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